

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**  
 Created on: **06/04/2022**

Details for "OMAPL137DZKB4"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
OMAPL137DZKB4	SNAGCU	Level-3-260C-168 HR	TI PHILIPPINES A/T	ZKB   256	17x17x1.36	914.1

**\*Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	1.944262	97.585731	975857	0.212696	2127
Nickel and Its Alloys	Nickel	7440-02-0	0.00001	0.000502	5	0.000001	0
Not Categorized	Proprietary Materials		0.000219	0.010992	110	0.000024	0
Precious Metals	Palladium	7440-05-3	0.047814	2.399864	23999	0.005231	52
Precious Metals	Silver	7440-22-4	0.000058	0.002911	29	0.000006	0
Sub-Total			<b>1.992363</b>	<b>100</b>	<b>1000000</b>	<b>0.217958</b>	<b>2180</b>
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	4.520763	81.999994	820000	0.494558	4946
Thermoplastics	Epoxy	85954-11-6	0.992363	18.000006	180000	0.108561	1086
Sub-Total			<b>5.513126</b>	<b>100</b>	<b>1000000</b>	<b>0.603119</b>	<b>6031</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Aluminum Nitride	24304-00-5	3.35615	1	10000	0.367153	3672
Other Inorganic Materials	Fused Silica	60676-86-0	284.702197	84.83	848300	31.145547	311455
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	3.691765	1.1	11000	0.403868	4039
Other Organic Materials	Bromine	7726-95-6	0.067123	0.02	200	0.007343	73
Other Organic Materials	Chlorine	7782-50-5	0.067123	0.02	200	0.007343	73
Other Plastics and Rubber	Carbon Black	1333-86-4	1.006845	0.3	3000	0.110146	1101
Other Plastics and Rubber	Silicone	218163-11-2	2.68492	0.8	8000	0.293722	2937
Thermoplastics	Epoxy	85954-11-6	40.038868	11.93	119300	4.380129	4380
Sub-Total			<b>335.614991</b>	<b>100</b>	<b>1000000</b>	<b>36.715251</b>	<b>367153</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	17.326358	100	1000000	1.89545	18955
Sub-Total			<b>17.326358</b>	<b>100</b>	<b>1000000</b>	<b>1.89545</b>	<b>18955</b>
<b>Solder Ball</b>							
Aluminum and Its Alloys	Aluminum	7429-90-5	0.002147	0.001	10	0.000235	2
Copper and Its Alloys	Copper	7440-50-8	1.073278	0.5	5000	0.117413	1174
Copper and Its Alloys	Iron	7439-89-6	0.042931	0.02	200	0.004697	47
Other Nonferrous Metals and Alloys	Antimony	7440-36-0	0.107328	0.05	500	0.011741	117
Other Nonferrous Metals and Alloys	Arsenic	7440-38-2	0.064397	0.03	300	0.007045	70
Other Nonferrous Metals and Alloys	Bismuth	7440-69-9	0.064397	0.03	300	0.007045	70
Other Nonferrous Metals and Alloys	Cadmium	7440-43-9	0.004293	0.002	20	0.00047	5
Other Nonferrous Metals and Alloys	Tin	7440-31-5	206.854986	96.365999	963660	22.629301	226293
Precious Metals	Silver	7440-22-4	6.439667	3	30000	0.70448	7045
Zinc and Its Alloys	Zinc	7440-66-6	0.002147	0.001	10	0.000235	2
Sub-Total			<b>214.655571</b>	<b>100</b>	<b>1000000</b>	<b>23.482661</b>	<b>234827</b>
<b>Substrate</b>							
Ceramics / Glass	Woven Glass Fiber	65997-17-3	28.851951	8.5109	85109	3.156315	31563
Copper and Its Alloys	Copper	7440-50-8	108.413556	31.9804	319804	11.860111	118601
Nickel and Its Alloys	Nickel	7440-02-0	5.785374	1.7066	17066	0.632902	6329
Other Inorganic Materials	Inorganic Filler		26.013165	7.6735	76735	2.84576	28458
Other Nonferrous Metals and Alloys	Barium Sulfate	7727-43-7	2.838786	0.8374	8374	0.310554	3106
Other Organic Materials	Bromine	7726-95-6	0.021018	0.0062	62	0.002299	23
Other Organic Materials	Chlorine	7782-50-5	0.064071	0.0189	189	0.007009	70
Precious Metals	Gold	7440-57-5	1.253622	0.3698	3698	0.137142	1371
Thermoplastics	Epoxy	85954-11-6	165.758457	48.8963	488963	18.133467	181335
Sub-Total			<b>339</b>	<b>100</b>	<b>1000000</b>	<b>37.08556</b>	<b>370856</b>
<b>Total</b>			<b>914.102409</b>			<b>100</b>	<b>1000000</b>

**Important Note**

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

[See Glossary of Terms for more details.](#)

**Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**

[For an explanation of the methods used to determine material weights, see Product Content Methodology.](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

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Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
 Created on: 06/04/2022

**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.